

ABSTRACT

DEVICE AND METHOD FOR MONITORING AN ELECTROLYTIC PROCESS

In manufacturing integrated circuits voids in the metal layer may readily form during electrolytic metal deposition. In order to avoid these faults which adversely affect the functionality of the circuits, the invention suggests to utilize for metal deposition an electrolysis device comprised of at least one anode and at least one cathode and in which at least one reference electrode is disposed at the surface of the at least one anode or at the surface of the at least one cathode. A voltmeter is respectively provided for detecting the electric voltages between the at least one anode and the at least one reference electrode and between the at least one reference electrode and the at least one cathode.